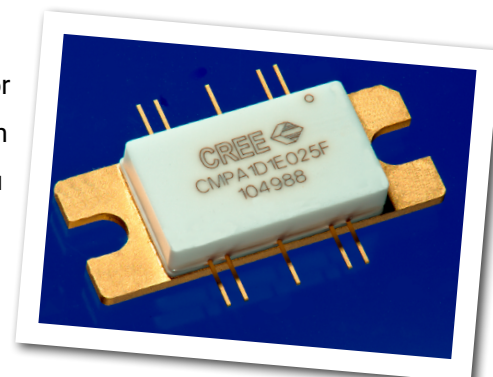


# CMPA1D1E025F

**25 W, 13.75 - 14.5 GHz, 40 V, Ku-Band GaN MMIC, Power Amplifier**

Cree's CMPA1D1E025F is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT) based monolithic microwave integrated circuit (MMIC) on a silicon carbide (SiC) substrate, using a 0.25  $\mu\text{m}$  gate length fabrication process. The Ku Band 25W MMIC is targeted for commercial Ku Band satellite communications applications. It offers high gain and superior efficiency while meets OQPSK linearity required for Satcom applications at 3dB backed off Psat operations. This Ku Band MMIC is available in a 10 lead, 25 mm x 9.9 mm metal/ceramic flanged package.



PN: CMPA1D1E025F  
Package Type:440208

## Typical Performance Over 13.75-14.5 GHz ( $T_c = 25^\circ\text{C}$ )

| Parameter              | 13.75 GHz | 14.0 GHz | 14.25 GHz | 14.5 GHz | Units |
|------------------------|-----------|----------|-----------|----------|-------|
| Small Signal Gain      | 24        | 24.5     | 24.5      | 24       | dB    |
| Linear Output Power    | 24        | 23       | 21        | 20       | W     |
| Power Gain             | 21        | 21       | 20        | 20       | dB    |
| Power Added Efficiency | 22        | 20       | 18        | 18       | %     |

Note<sup>1</sup>: Measured at -30 dBc, 1.6 MHz from carrier, in the CMPA1D1E025F-AMP under OQPSK modulation, 1.6 Msps, PN23, Alpha Filter = 0.2.

## Features

- 24 dB Small Signal Gain
- 40 W Typical Pulsed  $P_{\text{SAT}}$
- Operation up to 40 V
- 20 W linear power under OQPSK
- Class A/B high gain, high efficiency 50 ohm MMIC Ku Band high power amplifier

## Applications

- Satellite Communications Uplink

## Absolute Maximum Ratings (not simultaneous)

| Parameter                            | Symbol          | Rating    | Units    | Conditions                                  |
|--------------------------------------|-----------------|-----------|----------|---------------------------------------------|
| Drain-source Voltage                 | $V_{DS}$        | 84        | $V_{DC}$ | 25°C                                        |
| Gate-source Voltage                  | $V_{GS}$        | -10, +2   | $V_{DC}$ | 25°C                                        |
| Power Dissipation                    | $P_{DISS}$      | 94        | W        |                                             |
| Storage Temperature                  | $T_{STG}$       | -55, +150 | °C       |                                             |
| Operating Junction Temperature       | $T_J$           | 225       | °C       |                                             |
| Maximum Forward Gate Current         | $I_{GMAX}$      | 10        | mA       | 25°C                                        |
| Soldering Temperature <sup>1</sup>   | $T_S$           | 245       | °C       |                                             |
| Screw Torque                         | $\tau$          | 40        | in-oz    |                                             |
| Thermal Resistance, Junction to Case | $R_{\theta JC}$ | 1.5       | °C/W     | $P_{DISS} = 94 \text{ W}, 85^\circ\text{C}$ |
| Case Operating Temperature           | $T_C$           | -40, +85  | °C       | CW, $P_{DISS} = 94 \text{ W}$               |

Note:

<sup>1</sup> Refer to the Application Note on soldering at [www.cree.com/products/wireless\\_appnotes.asp](http://www.cree.com/products/wireless_appnotes.asp)

## Electrical Characteristics (Frequency = 13.75 GHz to 14.5 GHz unless otherwise stated; $T_C = 25^\circ\text{C}$ )

| Characteristics                       | Symbol       | Min. | Typ. | Max. | Units  | Conditions                                                                                                         |
|---------------------------------------|--------------|------|------|------|--------|--------------------------------------------------------------------------------------------------------------------|
| <b>DC Characteristics<sup>1</sup></b> |              |      |      |      |        |                                                                                                                    |
| Gate Threshold                        | $V_{GS(TH)}$ | -3.8 | -3.0 | -2.3 | V      | $V_{DS} = 10 \text{ V}, I_D = 18.2 \text{ mA}$                                                                     |
| Gate Quiescent Voltage                | $V_Q$        | –    | -2.7 | –    | V      | $V_{DS} = 40 \text{ V}, I_D = 240 \text{ mA}$                                                                      |
| Saturated Drain Current <sup>2</sup>  | $I_{DS}$     | 14.6 | 16.4 | –    | A      | $V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$                                                                   |
| Drain-Source Breakdown Voltage        | $V_{BD}$     | 84   | 100  | –    | V      | $V_{GS} = -8 \text{ V}, I_D = 18.2 \text{ mA}$                                                                     |
| <b>RF Characteristics<sup>3</sup></b> |              |      |      |      |        |                                                                                                                    |
| Small Signal Gain                     | S21          | –    | 24   | –    | dB     | $V_{DD} = 40 \text{ V}, I_{DQ} = 240 \text{ mA}, P_{IN} = -15 \text{ dBm}$                                         |
| Input Return Loss                     | S11          | –    | -7   | –    | dB     | $V_{DD} = 40 \text{ V}, I_{DQ} = 240 \text{ mA}, P_{IN} = -15 \text{ dBm}$                                         |
| Output Return Loss                    | S22          | –    | -7   | –    | dB     | $V_{DD} = 40 \text{ V}, I_{DQ} = 240 \text{ mA}, P_{IN} = -15 \text{ dBm}$                                         |
| Output Mismatch Stress                | VSWR         | –    | –    | 5:1  | $\Psi$ | No damage at all phase angles, $V_{DD} = 40 \text{ V}, I_{DQ} = 240 \text{ mA}$ , $P_{OUT} = 41 \text{ dBm}$ OQPSK |

Notes:

<sup>1</sup> Measured on-wafer prior to packaging.

<sup>2</sup> Scaled from PCM data.

<sup>3</sup> Measured in the CMPA1D1E025F-AMP

## Electrical Characteristics Continued... ( $T_c = 25^\circ\text{C}$ )

| Characteristics                             | Symbol   | Min. | Typ. | Max. | Units | Conditions                                                                   |
|---------------------------------------------|----------|------|------|------|-------|------------------------------------------------------------------------------|
| <b>RF Characteristics<sup>1,2,3,4</sup></b> |          |      |      |      |       |                                                                              |
| Power Added Efficiency                      | PAE1     | –    | 18.6 | –    | %     | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 13.75 GHz |
| Power Added Efficiency                      | PAE2     | –    | 16.4 | –    | %     | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 14.5 GHz  |
| Power Gain                                  | $G_{P1}$ | –    | 23.3 | –    | dB    | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 13.75 GHz |
| Power Gain                                  | $G_{P2}$ | –    | 22.1 | –    | dB    | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 14.5 GHz  |
| OQPSK Linearity                             | ACLR1    | –    | -40  | –    | dBc   | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 13.75 GHz |
| OQPSK Linearity                             | ACLR2    | –    | -38  | –    | dBc   | $V_{DD} = 40\text{ V}$ , $I_{DQ} = 240\text{ mA}$ ,<br>Frequency = 14.5 GHz  |

### Notes:

<sup>1</sup> Measured in the CMPA1D1E025F-AMP

<sup>2</sup> Under OQPSK modulated signal, 1.6 Msps, PN23, Alpha Filter = 0.2.

<sup>3</sup> Measured at  $P_{AVE} = 41\text{ dBm}$ .

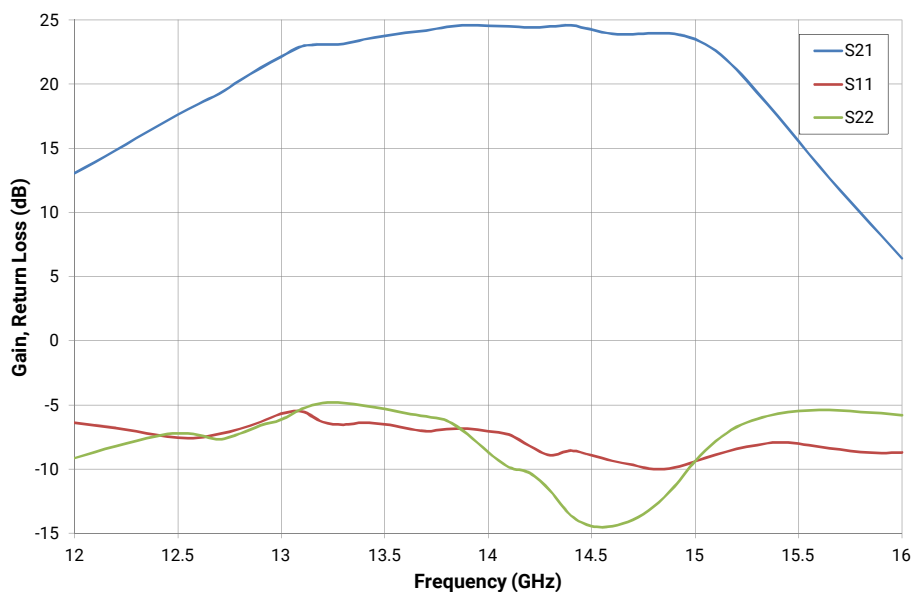
<sup>4</sup> Fixture loss de-embedded.

## Electrostatic Discharge (ESD) Classifications

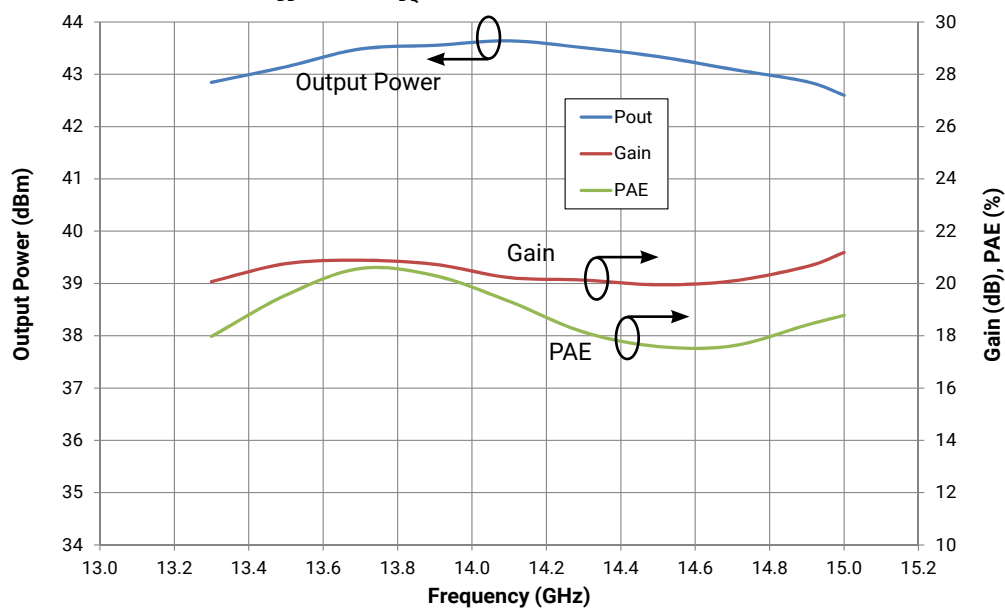
| Parameter           | Symbol | Class            | Test Methodology    |
|---------------------|--------|------------------|---------------------|
| Human Body Model    | HBM    | 1A (> 250 V)     | JEDEC JESD22 A114-D |
| Charge Device Model | CDM    | II (200 < 500 V) | JEDEC JESD22 C101-C |

## Typical Performance

**Figure 1. - Small Signal S-parameters**  
**CPA1D1E025F in Test Fixture**  
 $V_{DD} = 40V, I_{DQ} = 240\text{ mA}, T_{case} = 25^{\circ}C$

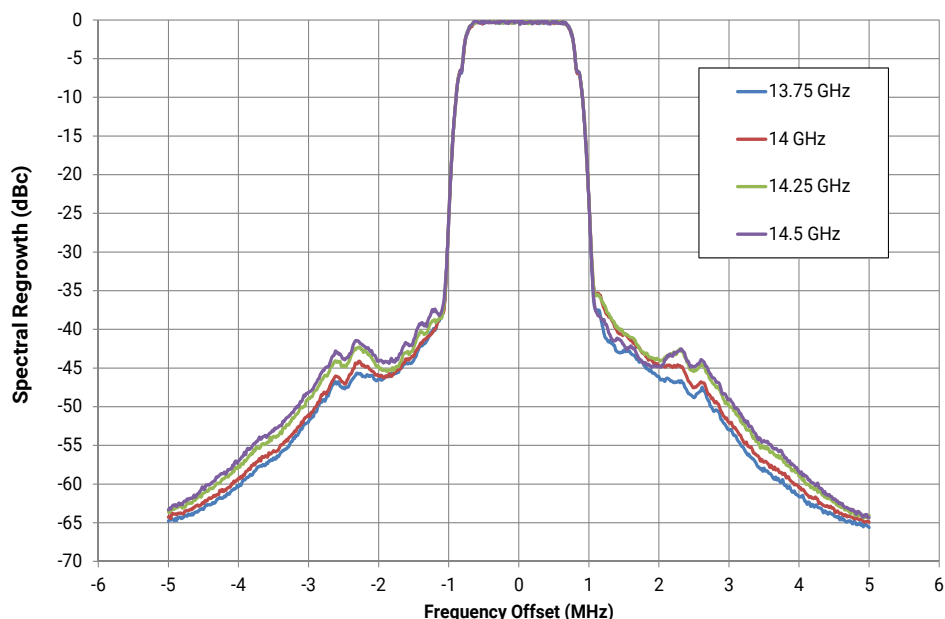


**Figure 2. - Modulated @ Spectral Regrowth = -30dBc, 1.6 MHz from Carrier**  
**1.6 Msps OQPSK Modulation**  
 $V_{DD} = 40\text{ V}, I_{DQ} = 240\text{ mA}, T_{case} = 25^{\circ}C$

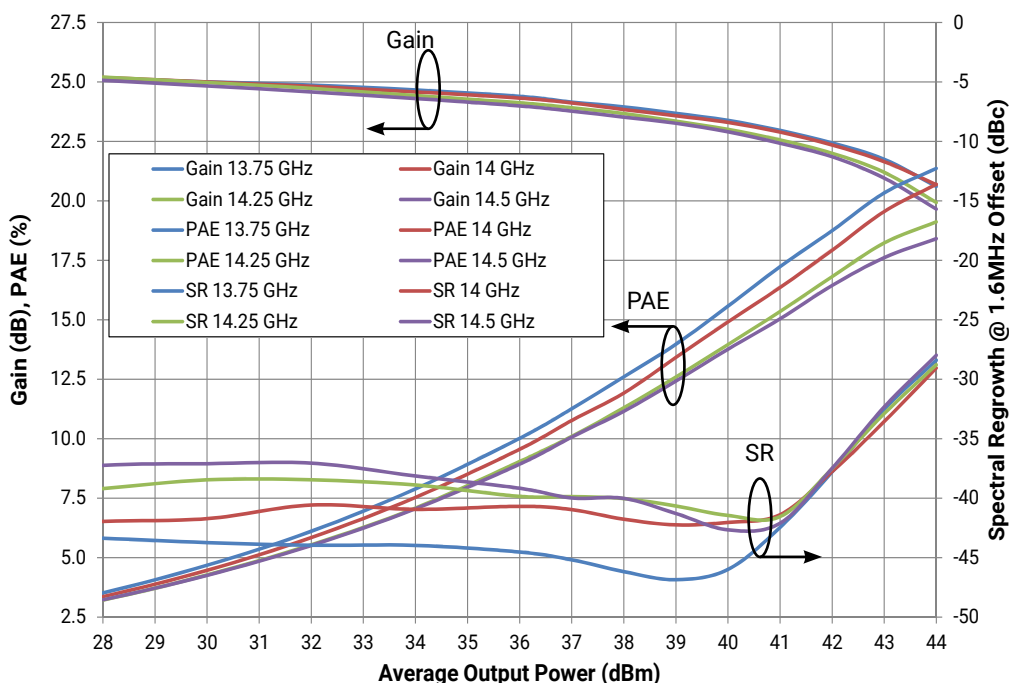


## Typical Performance

**Figure 3. - Spectral Mask @ Average Output Power = 41dBm**  
**1.6 Msps OQPSK Modulation**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^{\circ}\text{C}$

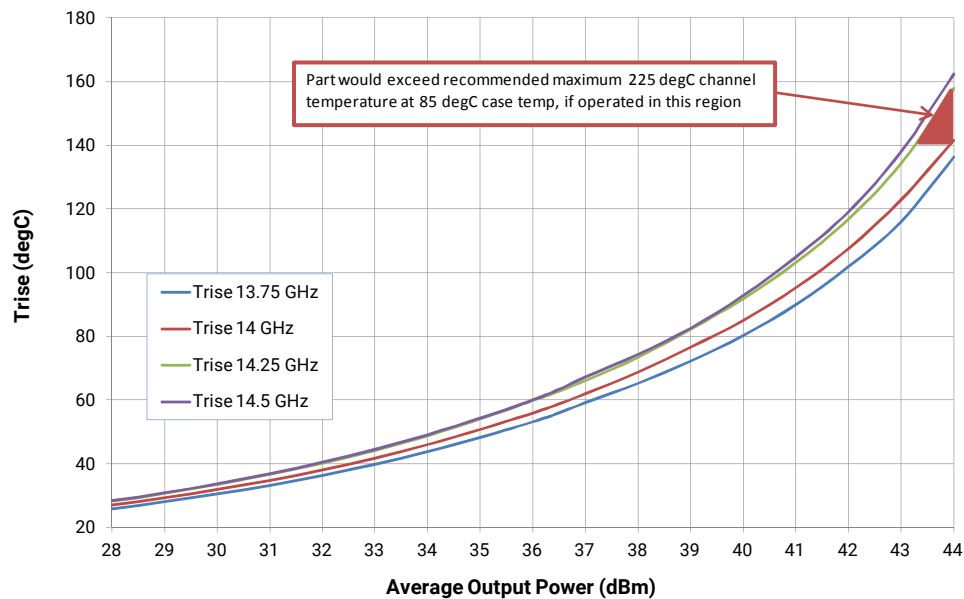


**Figure 4. - CMPA1D1E025F Modulated Power Sweep**  
**1.6 Msps OQPSK Modulation**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^{\circ}\text{C}$

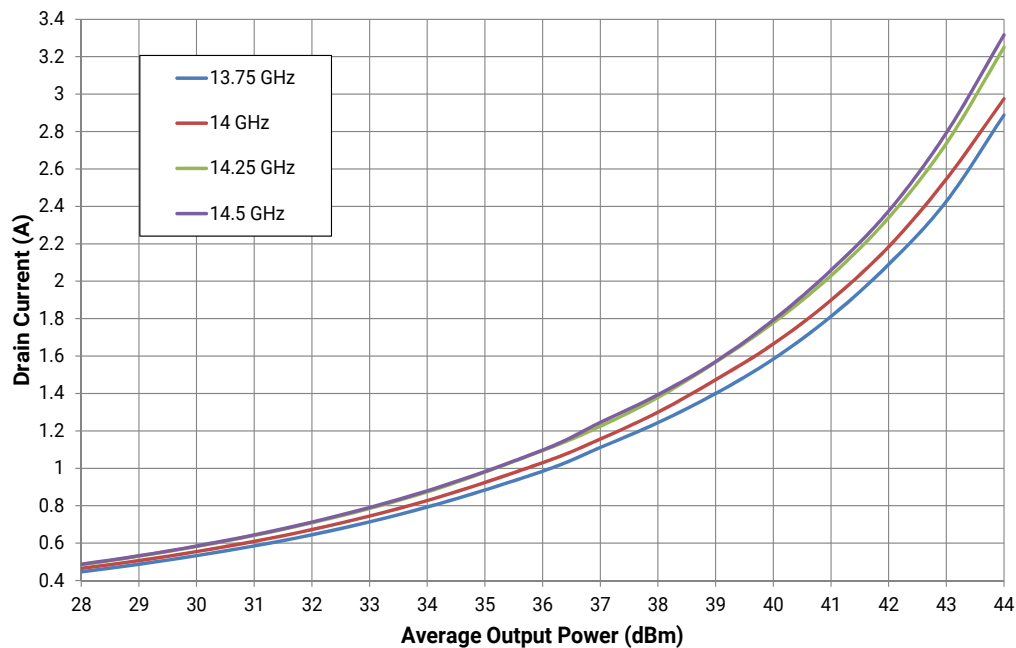


## Typical Performance

**Figure 5. - Modulated Power Sweep**  
**1.6 Msps QPSK Modulation**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$



**Figure 6. - CMPA1D1E025F Modulated Power Sweep**  
**1.6 Msps QPSK Modulation**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$

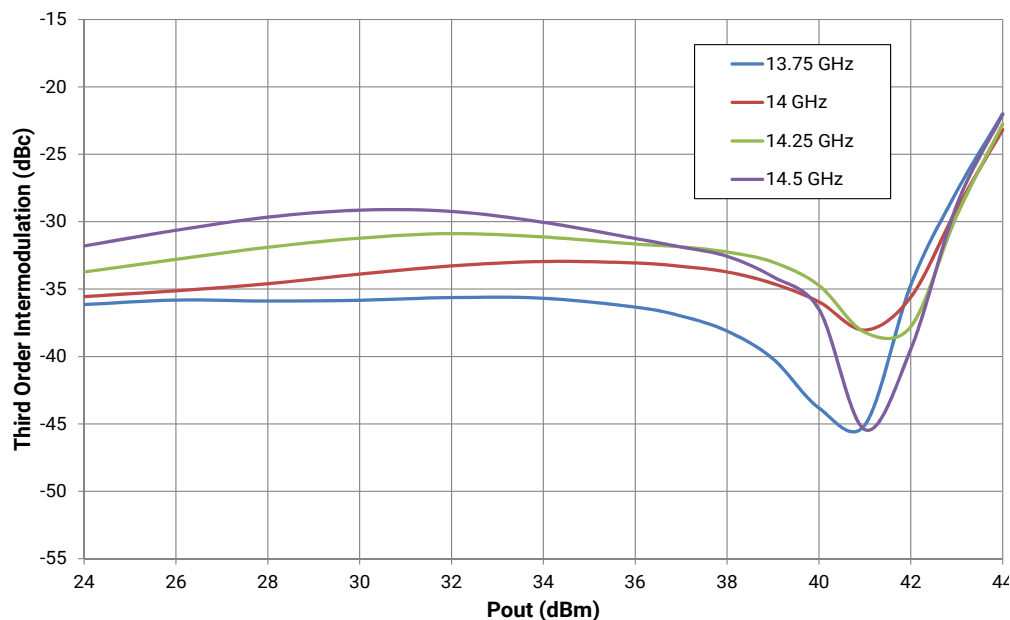


## Typical Performance

**Figure 7. - CMPA1D1E025F Two Tone Power Sweep**

**IMD3 @ 1 MHz Carrier Spacing**

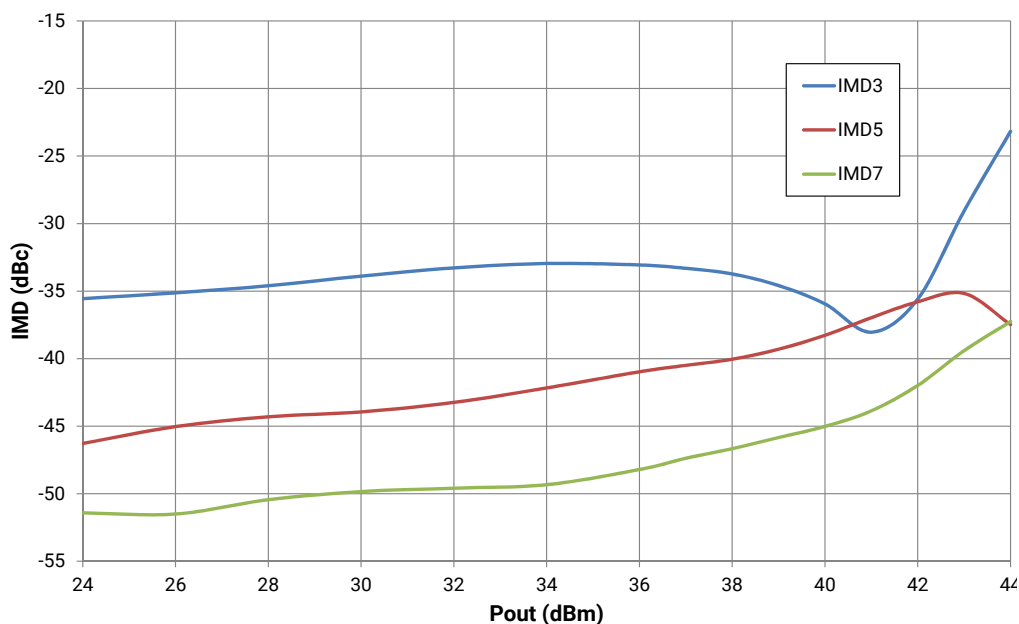
**$V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$**



**Figure 8. - Two Tone Power Sweep**

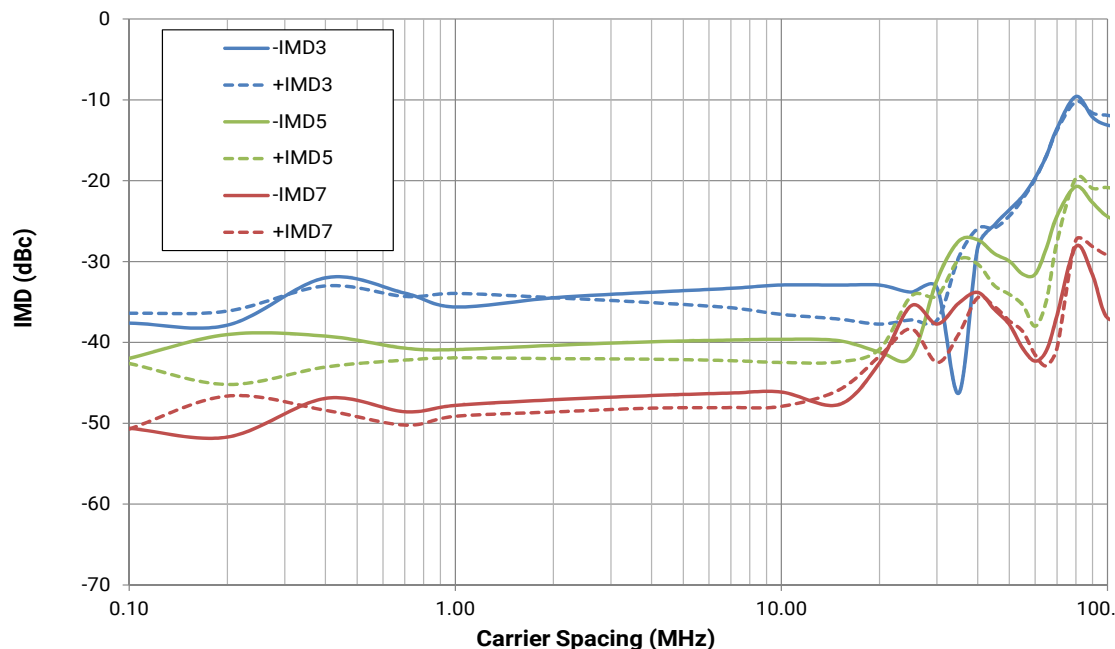
**IMD @ 1 MHz Carrier Spacing, 14 GHz**

**$V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$**

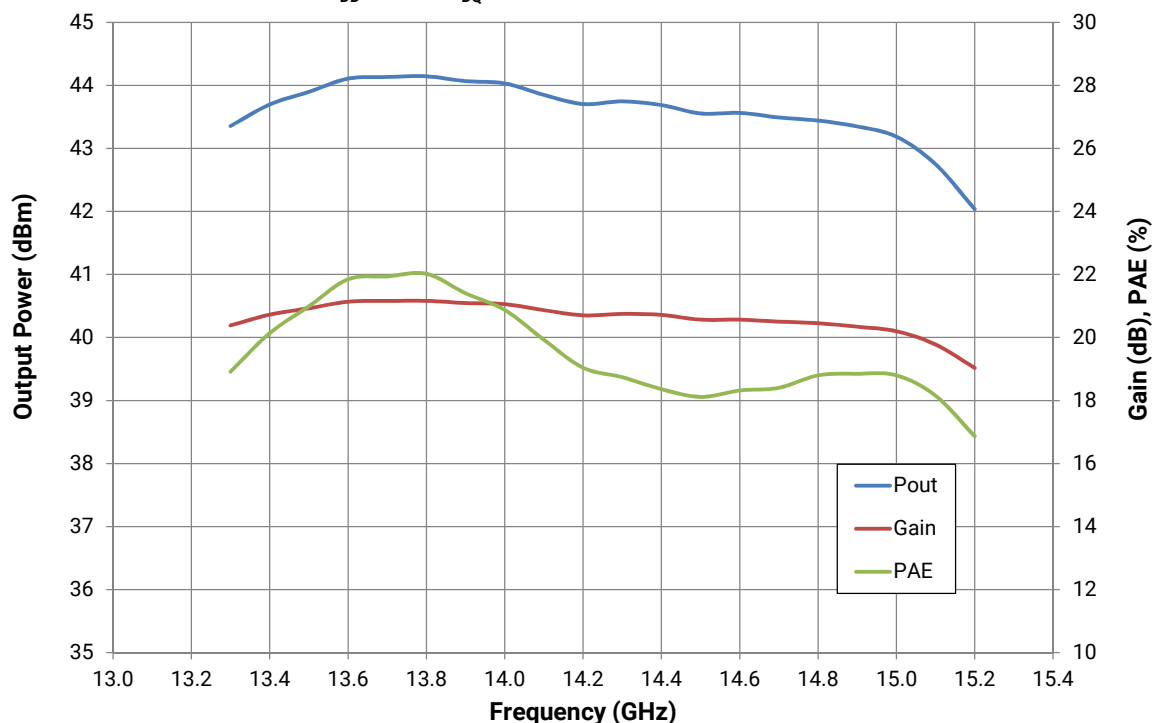


## Typical Performance

**Figure 9. - Two Tone Carrier Spacing Sweep @ 38 dBm Average Output Power, 14 GHz**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 1\text{ A}$ ,  $T_{case} = 25^\circ\text{C}$

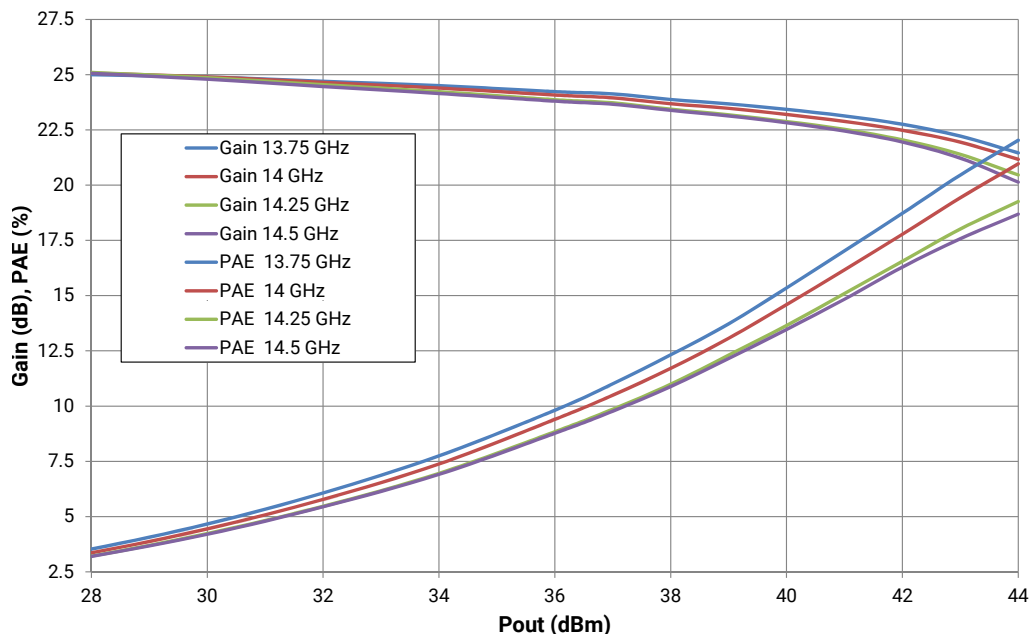


**Figure 10. - CW vs. Frequency @  $P_{IN} = 23\text{ dBm}$**   
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$

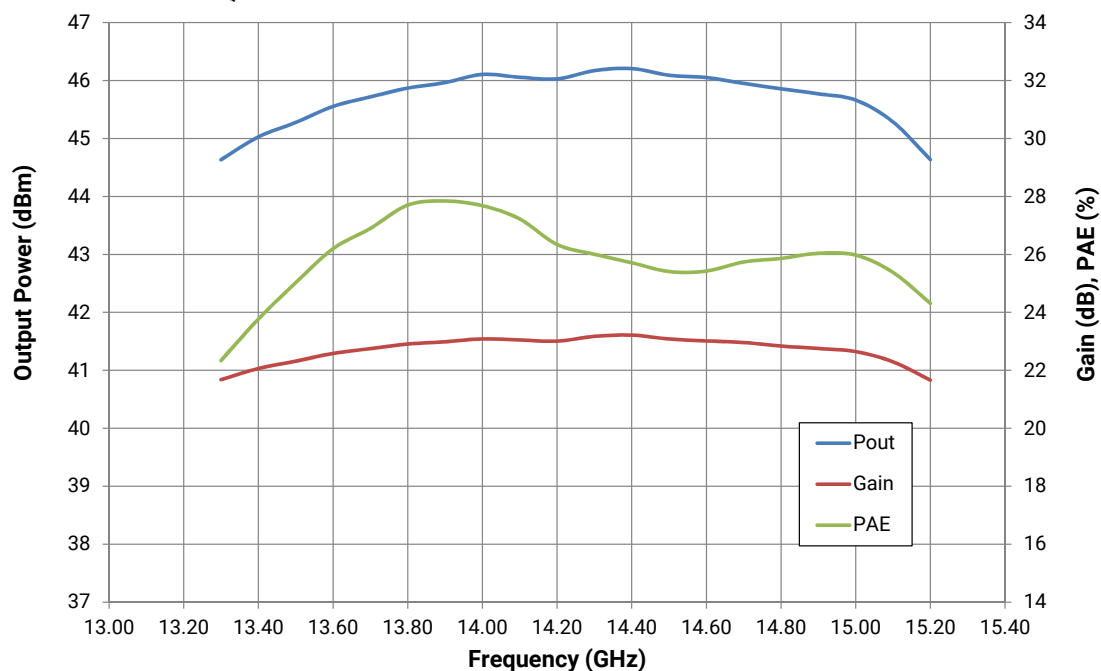


## Typical Performance

**Figure 11. - CW Power Sweep CMPA1D1E025F in Test Fixture**  
 $V_{DD} = 40V$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^{\circ}C$

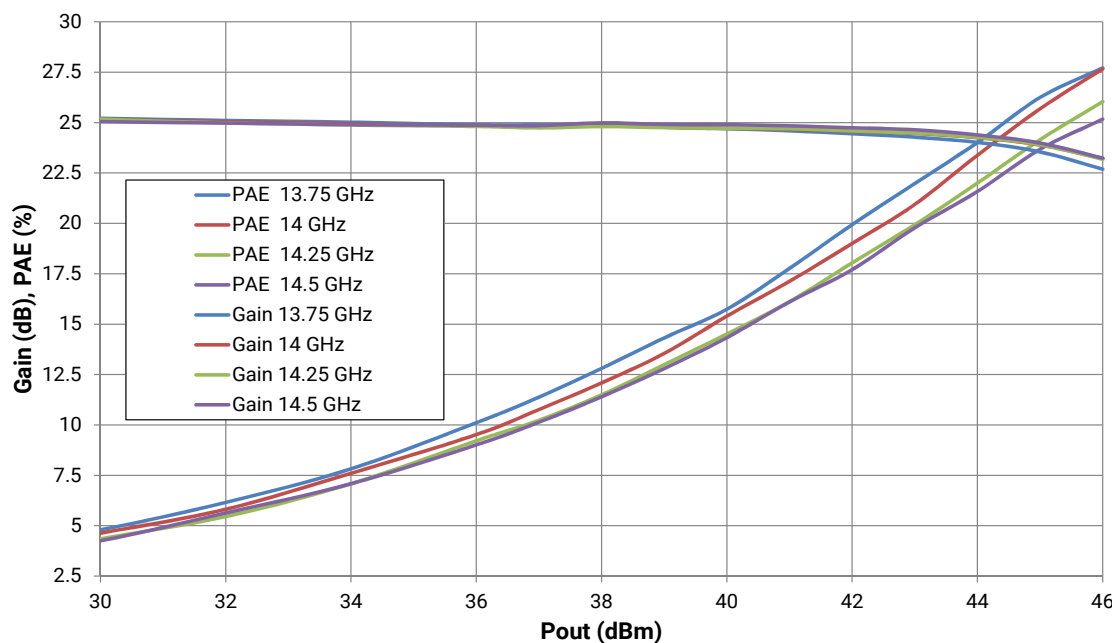


**Figure 12. - Pulsed vs. Frequency @  $P_{IN} = 23\text{ dBm}$  CMPA1D1E025F in Test Fixture**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ , 100  $\mu\text{s}$  Pulse Width, 10% Duty Cycle,  $T_{case} = 25^{\circ}C$

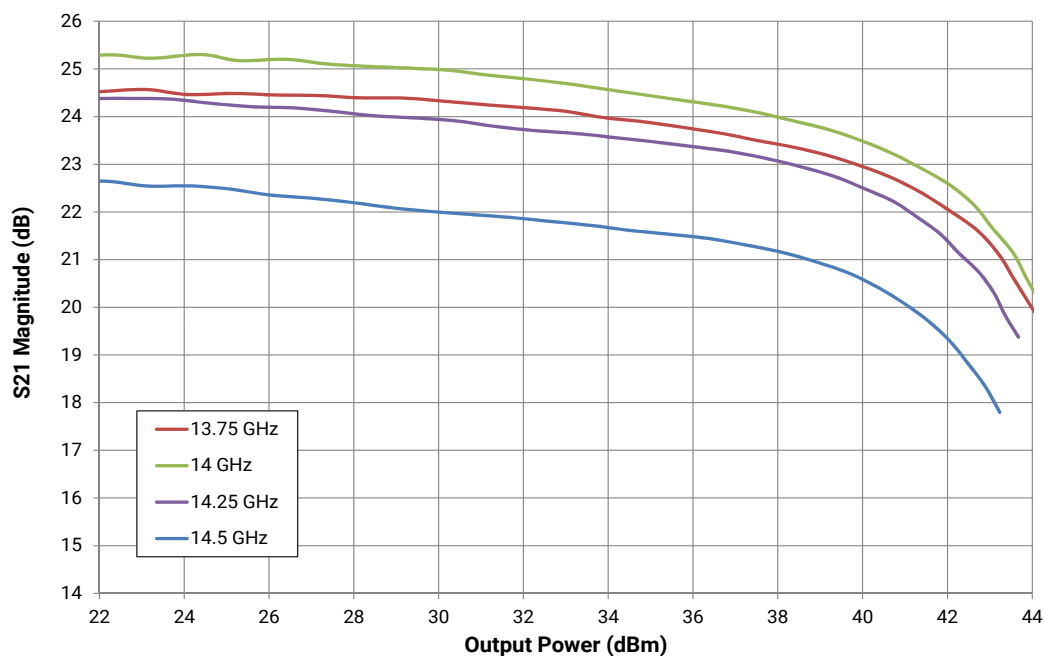


## Typical Performance

**Figure 13. - Pulsed Power Sweep CMPA1D1E025F in Test Fixture**  
 10% Duty, 100  $\mu$ s Pulse Width  
 $V_{DD} = 40V$ ,  $I_{DQ} = 240$  mA,  $T_{case} = 25^{\circ}C$

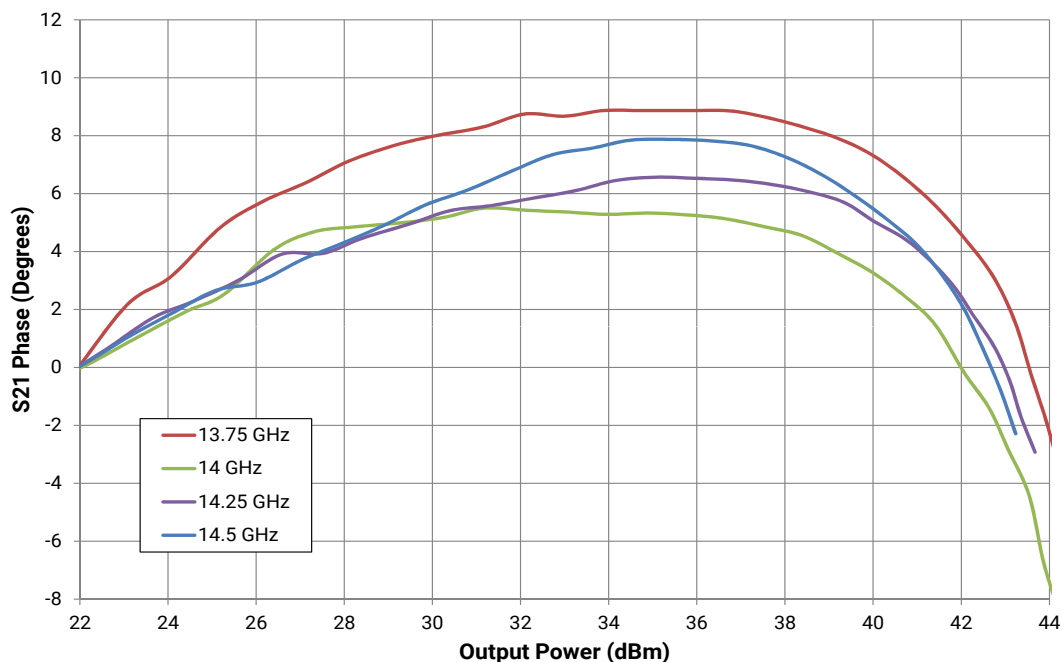


**Figure 14. - AM-AM**  
 $V_{DD} = 40$  V,  $I_{DQ} = 240$  mA,  $T_{case} = 25^{\circ}C$

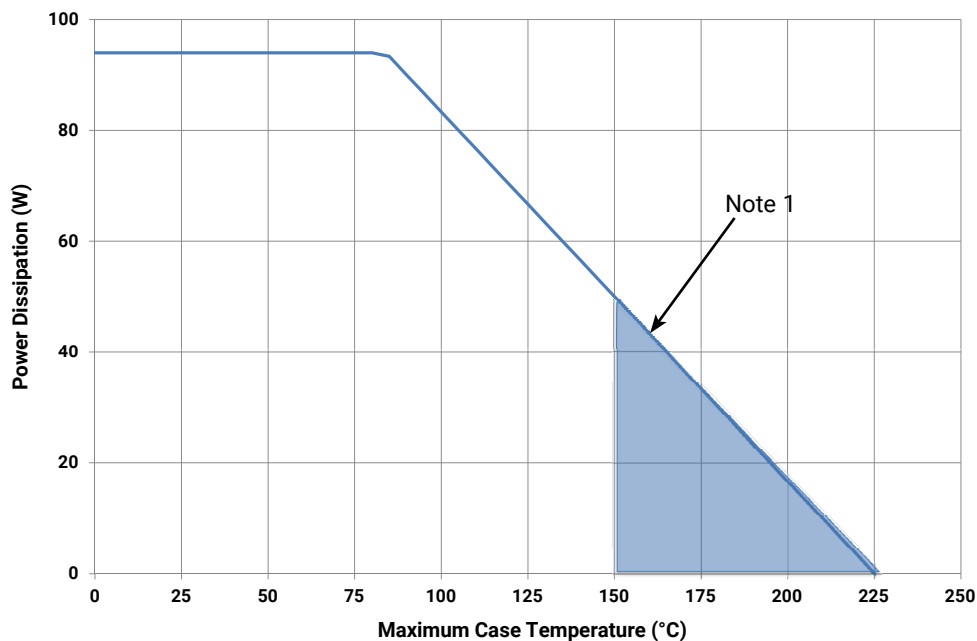


## Typical Performance

**Figure 15. - AM-PM**  
 $V_{DD} = 40\text{ V}$ ,  $I_{DQ} = 240\text{ mA}$ ,  $T_{case} = 25^\circ\text{C}$



## CMPA1D1E025F Power Dissipation De-rating Curve

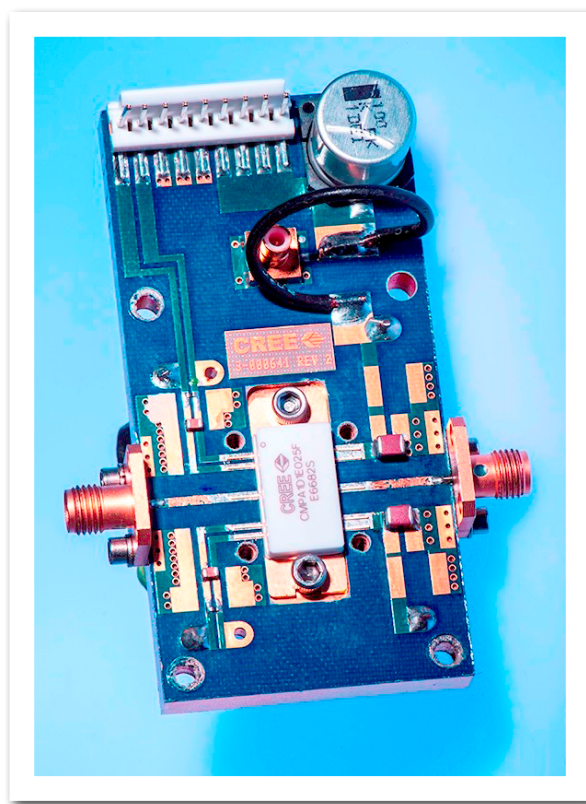


Note 1. Area exceeds Maximum Case Temperature (See Page 2).

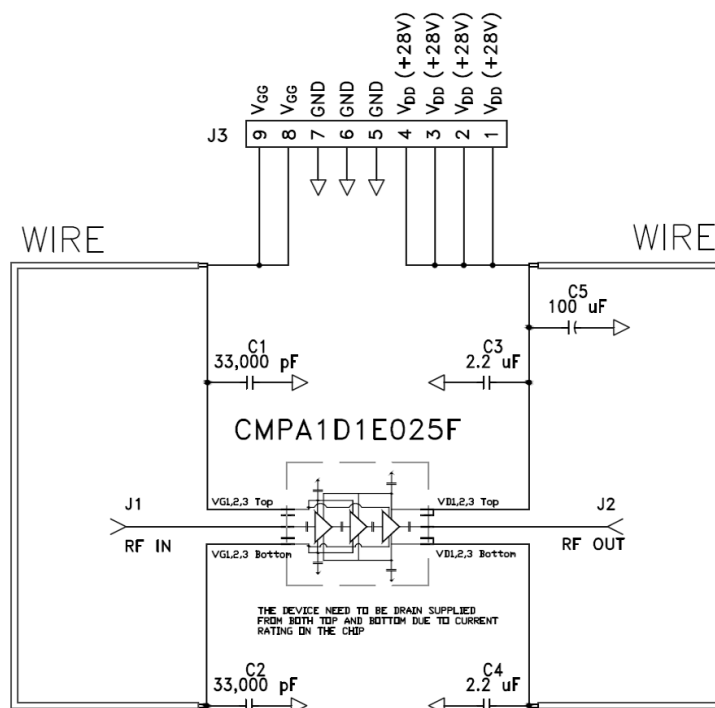
## CMPA1D1E025F-AMP Demonstration Amplifier Circuit Bill of Materials

| Designator | Description                                                    | Qty |
|------------|----------------------------------------------------------------|-----|
| C5         | CAP ELECT 100UF 80V AFK SMD                                    | 1   |
| C1,C2      | CAP, 33000PF, 0805,100V, X7R                                   | 2   |
| C3,C4      | CAP, 2.2UF, 100V, 10%, X7R, 1210                               | 4   |
| J1,J2      | CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST, 20MIL | 2   |
| J4         | CONN, SMB, STRAIGHT JACK RECEPTACLE, SMT, 50 OHM, Au PLATED    | 1   |
| J3         | HEADER RT>PLZ .1CEN LK 9POS                                    | 1   |
| W1         | WIRE, BLACK, 22 AWG ~ 1.50"                                    | 1   |
| W2         | WIRE, BLACK, 22 AWG ~ 1.75"                                    | 1   |
| W3         | WIRE, BLACK, 22 AWG ~ 2.0"                                     | 1   |
|            | PCB, TEST FIXTURE, TACONICS RF35P, 20 MILS, 440208 PKG         | 1   |
|            | 2-56 SOC HD SCREW 1/4 SS                                       | 4   |
| -          | #2 SPLIT LOCKWASHER SS                                         | 4   |
| Q1         | CMPA1D1E025F                                                   | 1   |

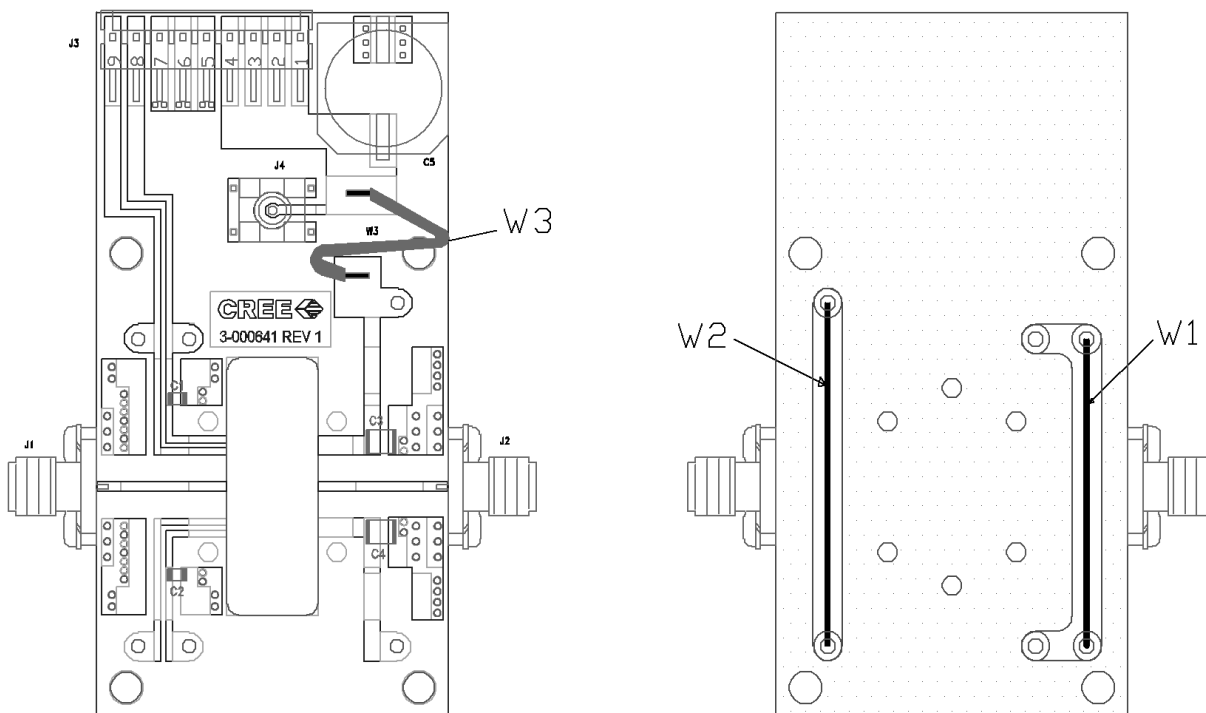
## CMPA1D1E025F-AMP Demonstration Amplifier Circuit



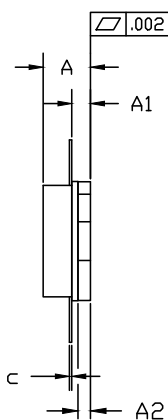
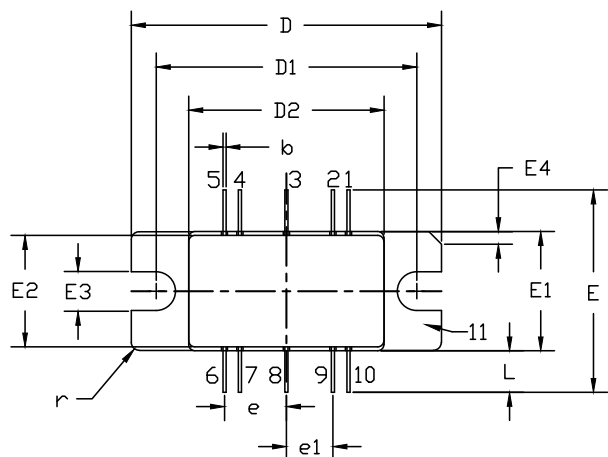
## CMPA1D1E025F-AMP Demonstration Amplifier Circuit Schematic



## CMPA1D1E025F-AMP Demonstration Amplifier Circuit Outline



## Product Dimensions CMPA1D1E025F (Package Type – 440208)



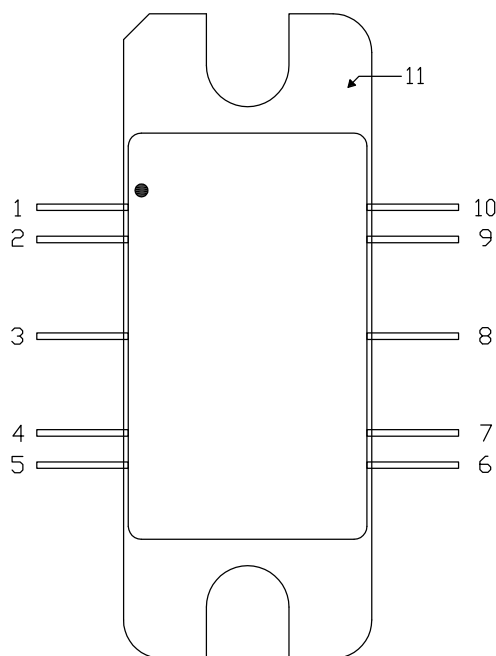
PIN 1: GATE BIAS 6: DRAIN BIAS  
 2: GATE BIAS 7: DRAIN BIAS  
 3: RF IN 8: RF OUT  
 4: GATE BIAS 9: DRAIN BIAS  
 5: GATE BIAS 10: DRAIN BIAS  
 11: SOURCE

### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1994.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.

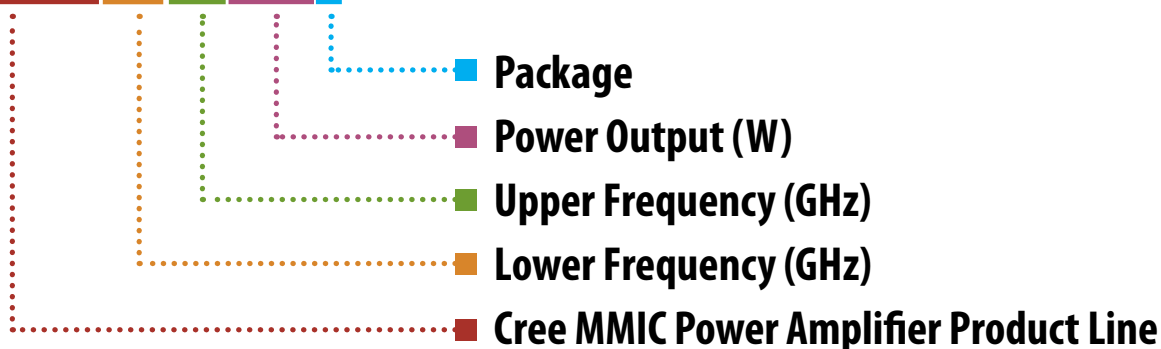
| DIM | INCHES |       | MILLIMETERS |       | NOTES       |
|-----|--------|-------|-------------|-------|-------------|
|     | MIN    | MAX   | MIN         | MAX   |             |
| A   | 0.148  | 0.168 | 3.76        | 4.27  |             |
| A1  | 0.055  | 0.065 | 1.40        | 1.65  |             |
| A2  | 0.035  | 0.045 | 0.89        | 1.14  |             |
| b   | 0.01   | TYP   | 0.254       | TYP   | 10x         |
| c   | 0.007  | 0.009 | 0.18        | 0.23  |             |
| D   | 0.995  | 1.005 | 25.27       | 25.53 |             |
| D1  | 0.835  | 0.845 | 21.21       | 21.46 |             |
| D2  | 0.623  | 0.637 | 15.82       | 16.18 |             |
| E   | 0.653  | TYP   | 16.59       | TYP   |             |
| E1  | 0.380  | 0.390 | 9.65        | 9.91  |             |
| E2  | 0.355  | 0.365 | 9.02        | 9.27  |             |
| E3  | 0.120  | 0.130 | 3.05        | 3.30  |             |
| E4  | 0.035  | 0.045 | 0.89        | 1.14  | 45° CHAMFER |
| e   | 0.200  | TYP   | 5.08        | TYP   | 4x          |
| e1  | 0.150  | TYP   | 3.81        | TYP   | 4x          |
| L   | 0.115  | 0.155 | 2.92        | 3.94  | 10x         |
| r   | 0.025  | TYP   | .635        | TYP   | 3x          |

| Pin Number | Qty        |
|------------|------------|
| 1          | Gate Bias  |
| 2          | NC         |
| 3          | RF In      |
| 4          | NC         |
| 5          | Gate Bias  |
| 6          | Drain Bias |
| 7          | Drain Bias |
| 8          | RF Out     |
| 9          | Drain Bias |
| 10         | Drain Bias |
| 11         | Source     |



## Part Number System

### CMPA1D1E025F



| Parameter                    | Value  | Units |
|------------------------------|--------|-------|
| Lower Frequency              | 13.75  | GHz   |
| Upper Frequency <sup>1</sup> | 14.5   | GHz   |
| Power Output                 | 25     | W     |
| Package                      | Flange | -     |

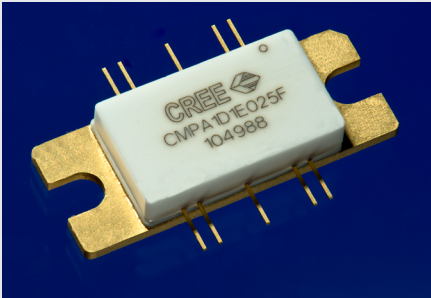
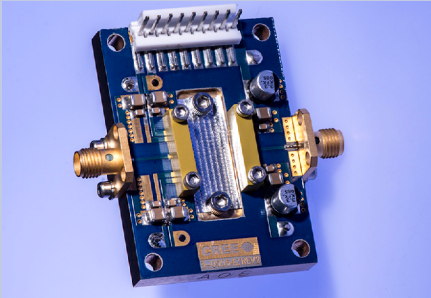
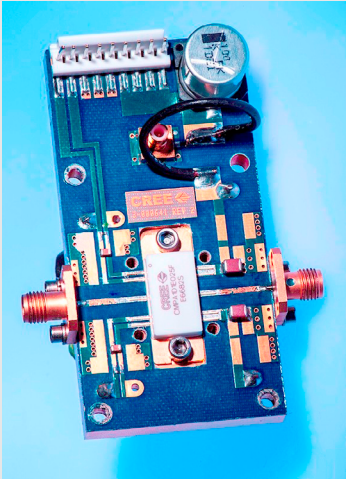
**Table 1.**

**Note<sup>1</sup>:** Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

| Character Code | Code Value                     |
|----------------|--------------------------------|
| A              | 0                              |
| B              | 1                              |
| C              | 2                              |
| D              | 3                              |
| E              | 4                              |
| F              | 5                              |
| G              | 6                              |
| H              | 7                              |
| J              | 8                              |
| K              | 9                              |
| Examples:      | 1A = 10.0 GHz<br>2H = 27.0 GHz |

**Table 2.**

Product Ordering Information

| Order Number     | Description                        | Unit of Measure | Image                                                                                 |
|------------------|------------------------------------|-----------------|---------------------------------------------------------------------------------------|
| CMPA1D1E025F     | GaN HEMT                           | Each            |    |
| CMPA1D1E025F-TB  | Test board without GaN HEMT        | Each            |   |
| CMPA1D1E025F-AMP | Test board with GaN HEMT installed | Each            |  |

## Disclaimer

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